

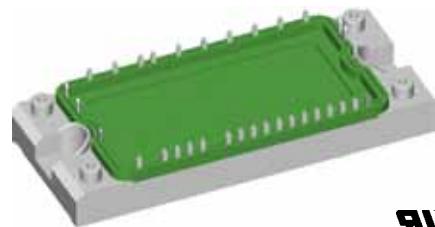
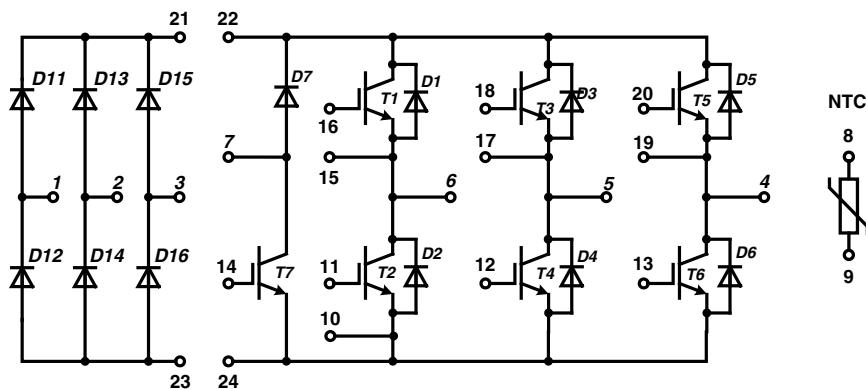
Converter - Brake - Inverter Module

XPT IGBT

Three Phase Rectifier	Brake Chopper	Three Phase Inverter
$V_{RRM} = 1600 \text{ V}$	$V_{CES} = 1200 \text{ V}$	$V_{CES} = 1200 \text{ V}$
$I_{DAVM} = 105 \text{ A}$	$I_{C25} = 17 \text{ A}$	$I_{C25} = 43 \text{ A}$
$I_{FSM} = 320 \text{ A}$	$V_{CE(sat)} = 1.8 \text{ V}$	$V_{CE(sat)} = 1.8 \text{ V}$

Part name (Marking on product)

MIXA30WB1200TED



E 72873

Pin configuration see outlines.

Features:

- Easy paralleling due to the positive temperature coefficient of the on-state voltage
- Rugged XPT design
(Xtreme light Punch Through) results in:
 - short circuit rated for 10 μsec .
 - very low gate charge
 - low EMI
- Thin wafer technology combined with the XPT design results in a competitive low $V_{CE(sat)}$
- SONIC™ diode
 - fast and soft reverse recovery
 - low operating forward voltage

Application:

- AC motor drives
- Solar inverter
- Medical equipment
- Uninterruptible power supply
- Air-conditioning systems
- Welding equipment
- Switched-mode and resonant-mode power supplies

Package:

- "E2-Pack" standard outline
- Insulated copper base plate
- Soldering pins for PCB mounting
- Temperature sense included

Output Inverter T1 - T6

Ratings

Symbol	Definitions	Conditions	min.	typ.	max.	Unit
V_{CES}	collector emitter voltage	$T_{VJ} = 25^\circ C$		1200		V
V_{GES}	max. DC gate voltage	continuous		± 20		V
V_{GEM}	max. transient collector gate voltage	transient		± 30		V
I_{C25}	collector current	$T_C = 25^\circ C$		43		A
I_{C80}		$T_C = 80^\circ C$		30		A
P_{tot}	total power dissipation	$T_C = 25^\circ C$		150		W
$V_{CE(sat)}$	collector emitter saturation voltage	$I_C = 25 A; V_{GE} = 15 V$	$T_{VJ} = 25^\circ C$ $T_{VJ} = 125^\circ C$	1.8 2.1	2.1	V
$V_{GE(th)}$	gate emitter threshold voltage	$I_C = 1 mA; V_{GE} = V_{CE}$	$T_{VJ} = 25^\circ C$	5.4	6.0	V
I_{CES}	collector emitter leakage current	$V_{CE} = V_{CES}; V_{GE} = 0 V$	$T_{VJ} = 25^\circ C$ $T_{VJ} = 125^\circ C$	0.02 0.2	1.5	mA mA
I_{GES}	gate emitter leakage current	$V_{GE} = \pm 20 V$		500		nA
$Q_{G(on)}$	total gate charge	$V_{CE} = 600 V; V_{GE} = 15 V; I_C = 25 A$		76		nC
$t_{d(on)}$ t_r $t_{d(off)}$ t_f E_{on} E_{off}	turn-on delay time current rise time turn-off delay time current fall time turn-on energy per pulse turn-off energy per pulse	inductive load $V_{CE} = 600 V; I_C = 15 A$ $V_{GE} = \pm 15 V; R_G = 39 \Omega$	$T_{VJ} = 125^\circ C$	70 40 250 100 2.5 3.0		ns ns ns ns mJ mJ
RBSOA	reverse bias safe operating area	$V_{GE} = \pm 15 V; R_G = 39 \Omega;$	$T_{VJ} = 125^\circ C$ $V_{CEK} = 1200 V$		75	A
SCSOA	short circuit safe operating area					
t_{sc} I_{sc}	short circuit duration short circuit current	$V_{CE} = 900 V; V_{GE} = \pm 15 V;$ $R_G = 39 \Omega$; non-repetitive	$T_{VJ} = 125^\circ C$	100	10	μs A
R_{thJC}	thermal resistance junction to case	(per IGBT)			0.84	K/W

Output Inverter D1 - D6

Ratings

Symbol	Definitions	Conditions	min.	typ.	max.	Unit
V_{RRM}	max. repetitive reverse voltage	$T_{VJ} = 25^\circ C$		1200		V
I_{F25}	forward current	$T_C = 25^\circ C$		44		A
I_{F80}		$T_C = 80^\circ C$		30		A
V_F	forward voltage	$I_F = 30 A; V_{GE} = 0 V$	$T_{VJ} = 25^\circ C$ $T_{VJ} = 125^\circ C$	1.95 1.95	2.2	V V
Q_{rr} I_{RM} t_{rr} E_{rec}	reverse recovery charge max. reverse recovery current reverse recovery time reverse recovery energy	$V_R = 600 V$ $di_F/dt = -600 A/\mu s$ $I_F = 30 A; V_{GE} = 0 V$	$T_{VJ} = 125^\circ C$	3.5 30 350 0.9		μC A ns mJ
R_{thJC}	thermal resistance junction to case	(per diode)			1.2	K/W

 $T_C = 25^\circ C$ unless otherwise stated

Brake T7

Ratings

Symbol	Definitions	Conditions	min.	typ.	max.	Unit
V_{CES}	collector emitter voltage	$T_{VJ} = 25^\circ C$		1200		V
V_{GES}	max. DC gate voltage	continuous		± 20		V
V_{GEM}	max. transient collector gate voltage	transient		± 30		V
I_{C25}	collector current	$T_C = 25^\circ C$	17		A	
I_{C80}		$T_C = 80^\circ C$	12		A	
P_{tot}	total power dissipation	$T_C = 25^\circ C$	60		W	
$V_{CE(sat)}$	collector emitter saturation voltage	$I_C = 9 A; V_{GE} = 15 V$	$T_{VJ} = 25^\circ C$ $T_{VJ} = 125^\circ C$	1.8 2.1	2.1	V
$V_{GE(th)}$	gate emitter threshold voltage	$I_C = 0.3 mA; V_{GE} = V_{CE}$	$T_{VJ} = 25^\circ C$	5.4	6.0	V
I_{CES}	collector emitter leakage current	$V_{CE} = V_{CES}; V_{GE} = 0 V$	$T_{VJ} = 25^\circ C$ $T_{VJ} = 125^\circ C$		0.1	mA
I_{GES}	gate emitter leakage current	$V_{GE} = \pm 20 V$			500	nA
$Q_{G(on)}$	total gate charge	$V_{CE} = 600 V; V_{GE} = 15 V; I_C = 10 A$	28		nC	
$t_{d(on)}$	turn-on delay time	$T_{VJ} = 125^\circ C$ $V_{CE} = 600 V; I_C = 10 A$ $V_{GE} = \pm 15 V; R_G = 100 \Omega$	70		ns	
t_r	current rise time		40		ns	
$t_{d(off)}$	turn-off delay time		250		ns	
t_f	current fall time		100		ns	
E_{on}	turn-on energy per pulse		1.1		mJ	
E_{off}	turn-off energy per pulse		1.1		mJ	
RBSOA	reverse bias safe operating area	$V_{GE} = \pm 15 V; R_G = 100 \Omega;$ $V_{CEK} = 1200 V$		30		A
SCSOA	short circuit safe operating area					
t_{sc}	short circuit duration	$V_{CE} = 900 V; V_{GE} = \pm 15 V;$ $R_G = 100 \Omega$; non-repetitive	$T_{VJ} = 125^\circ C$	10	μs	
I_{sc}	short circuit current			40	A	
R_{thJC}	thermal resistance junction to case	(per IGBT)		2.0	K/W	

Brake Chopper D7

Ratings

Symbol	Definitions	Conditions	min.	typ.	max.	Unit
V_{RRM}	max. repetitive reverse voltage	$T_{VJ} = 25^\circ C$		1200		V
I_{F25}	forward current	$T_C = 25^\circ C$	12		A	
I_{F80}		$T_C = 80^\circ C$	8		A	
V_F	forward voltage	$I_F = 5 A; V_{GE} = 0 V$	$T_{VJ} = 25^\circ C$ $T_{VJ} = 125^\circ C$	1.95 1.95	2.2	V
I_R	reverse current	$V_R = V_{RRM}$	$T_{VJ} = 25^\circ C$ $T_{VJ} = 125^\circ C$	0.5	0.5	mA
Q_{rr}	reverse recovery charge	$T_{VJ} = 125^\circ C$ $V_R = 600 V$ $di_F/dt = 200 A/\mu s$ $I_F = 5 A; V_{GE} = 0 V$	0.6		μC	
I_{RM}	max. reverse recovery current		6		A	
t_{rr}	reverse recovery time		350		ns	
E_{rec}	reverse recovery energy		0.2		mJ	
R_{thJC}	thermal resistance junction to case	(per diode)		3.4	K/W	

 $T_C = 25^\circ C$ unless otherwise stated

Input Rectifier Bridge D11 - D16

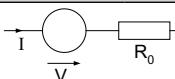
Ratings						
Symbol	Definitions	Conditions	min.	typ.	max.	Unit
V_{RRM}	max. repetitive reverse voltage		$T_{VJ} = 25^\circ\text{C}$		1600	V
I_{FAV}	average forward current	sine 180°	$T_C = 80^\circ\text{C}$		37	A
I_{DAVM}	max. average DC output current	rect.; $d = 1/3$	$T_C = 80^\circ\text{C}$		105	A
I_{FSM}	max. forward surge current	$t = 10 \text{ ms}; \text{sine } 50 \text{ Hz}$	$T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 125^\circ\text{C}$		320 280	A A
I^2t	I^2t value for fusing	$t = 10 \text{ ms}; \text{sine } 50 \text{ Hz}$	$T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 125^\circ\text{C}$		510 390	A ² s A ² s
P_{tot}	total power dissipation		$T_C = 25^\circ\text{C}$		110	W
V_F	forward voltage	$I_F = 50 \text{ A}$	$T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 125^\circ\text{C}$	1.34 1.34	1.7	V V
I_R	reverse current	$V_R = V_{RRM}$	$T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 125^\circ\text{C}$		0.02	mA mA
R_{thJC}	thermal resistance junction to case	(per diode)			1.1	K/W

Temperature Sensor NTC

Ratings						
Symbol	Definitions	Conditions	min.	typ.	max.	Unit
R_{25}	resistance		$T_C = 25^\circ\text{C}$	4.75	5.0	kΩ
$B_{25/50}$					3375	K

Module

Ratings						
Symbol	Definitions	Conditions	min.	typ.	max.	Unit
T_{VJ}	operating temperature		-40		125	°C
T_{VJM}	max. virtual junction temperature				150	°C
T_{stg}	storage temperature		-40		125	°C
V_{ISOL}	isolation voltage	$I_{ISOL} \leq 1 \text{ mA}; 50/60 \text{ Hz}$			2500	V~
CTI	comparative tracking index				-	
M_d	mounting torque (M5)		3		6	Nm
d_s	creep distance on surface		6			mm
d_A	strike distance through air		6			mm
$R_{pin-chip}$	resistance pin to chip				5	mΩ
R_{thCH}	thermal resistance case to heatsink	with heatsink compound		0.02		K/W
Weight					180	g

Equivalent Circuits for Simulation

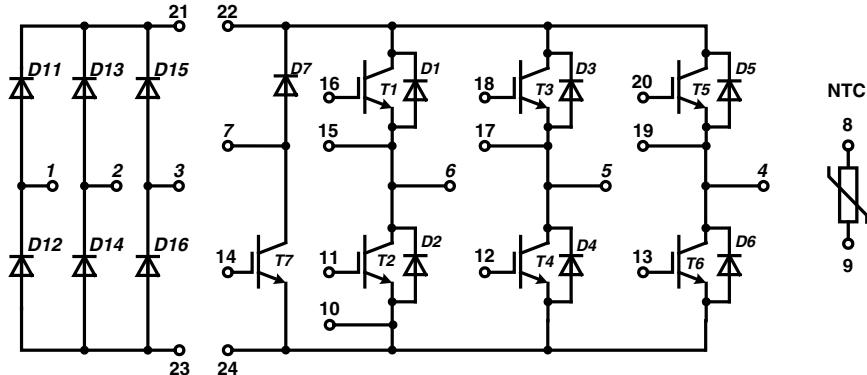
Ratings						
Symbol	Definitions	Conditions	min.	typ.	max.	Unit
V_0	rectifier diode	D8 - D13	$T_{VJ} = 150^\circ\text{C}$		0.88	V
R_0					9	mΩ
V_0	IGBT	T1 - T6	$T_{VJ} = 150^\circ\text{C}$		1.1	V
R_0					55	mΩ
V_0	free wheeling diode	D1 - D6	$T_{VJ} = 150^\circ\text{C}$		1.2	V
R_0					27	mΩ
V_0	IGBT	T7	$T_{VJ} = 150^\circ\text{C}$		1.1	V
R_0					153	mΩ
V_0	free wheeling diode	D7	$T_{VJ} = 150^\circ\text{C}$		1.15	V
R_0					170	mΩ

$T_C = 25^\circ\text{C}$ unless otherwise stated

IXYS reserves the right to change limits, test conditions and dimensions.

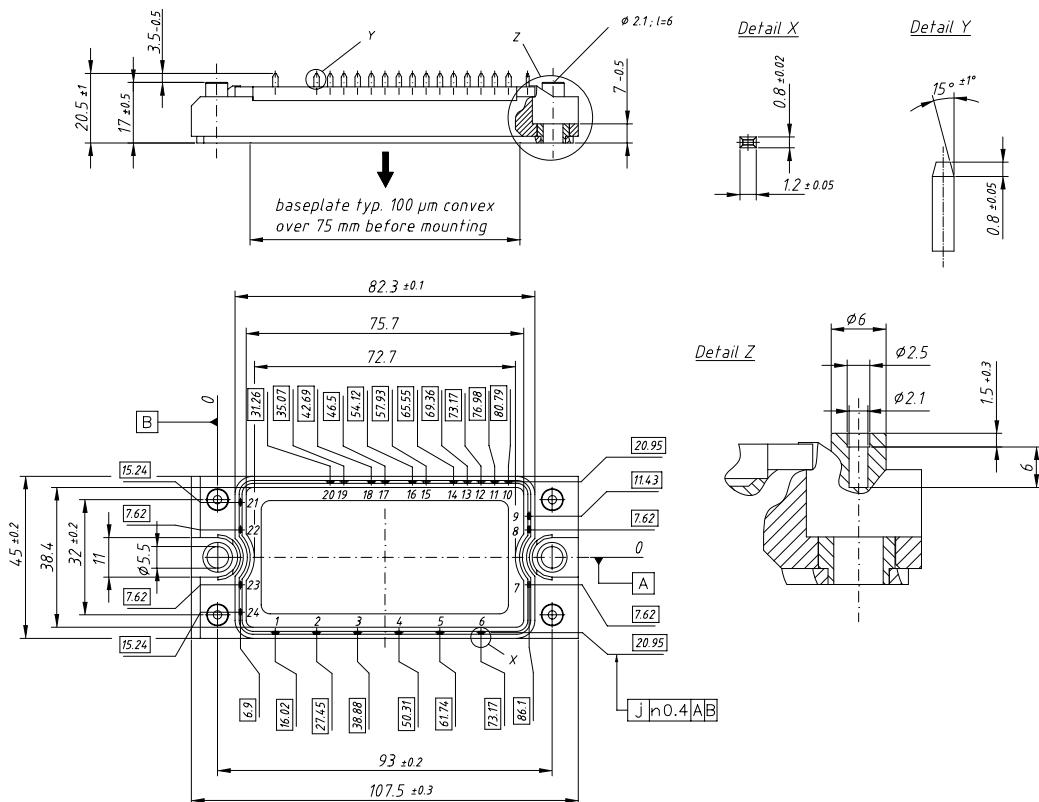
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Circuit Diagram

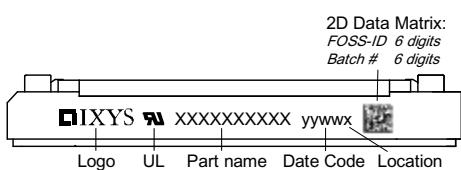


Outline Drawing

Dimensions in mm (1 mm = 0.0394")



Product Marking



2D Data Matrix:
FOSS-ID 6 digits
Batch # 6 digits

Part number

M = Module
I = IGBT
X = XPT
A = Standard
30 = Current Rating [A]
WB = 6-Pack + 3~ Rectifier Bridge & Brake Unit
1200 = Reverse Voltage [V]
T = NTC
ED = E2-Pack

Ordering	Part Name	Marking on Product	Delivering Mode	Base Qty	Ordering Code
Standard	MIXA30WB1200 TED	MIXA30WB1200TED	Box	6	509 119

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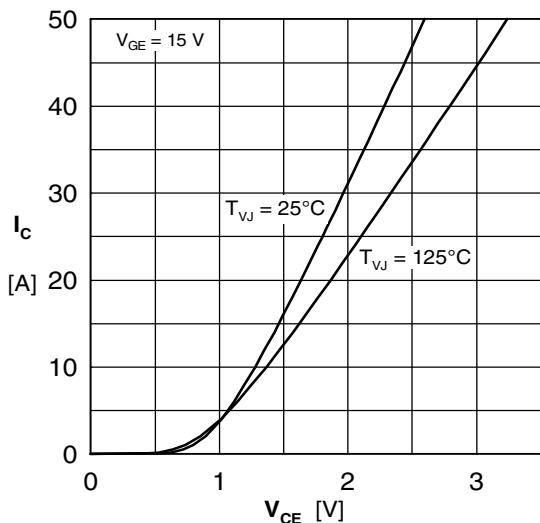
Inverter T1 - T6


Fig. 1 Typ. output characteristics

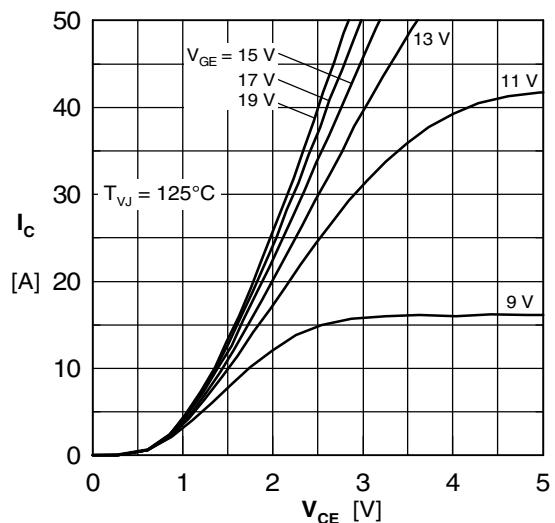


Fig. 2 Typ. output characteristics

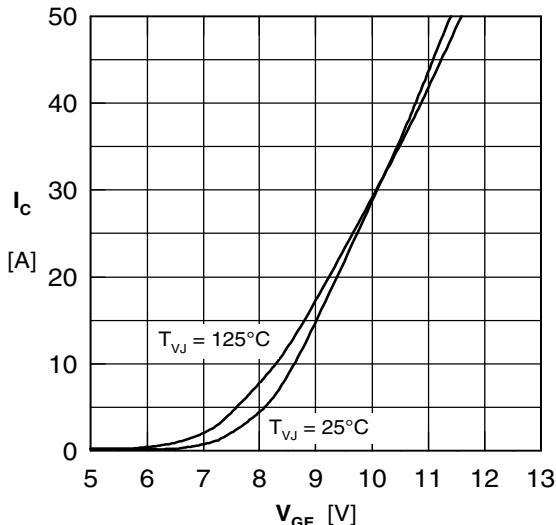


Fig. 3 Typ. tranfer characteristics

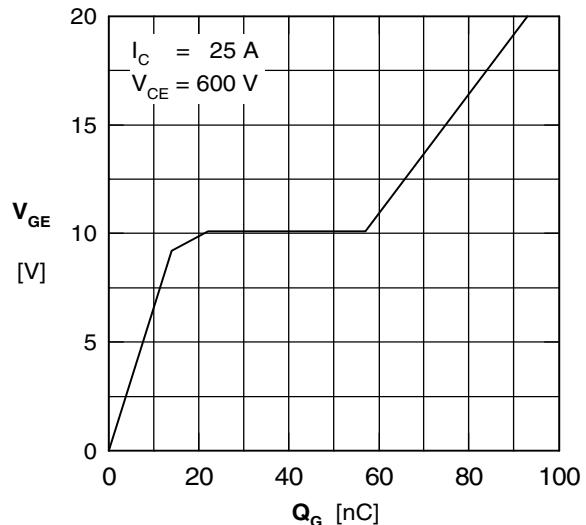


Fig. 4 Typ. turn-on gate charge

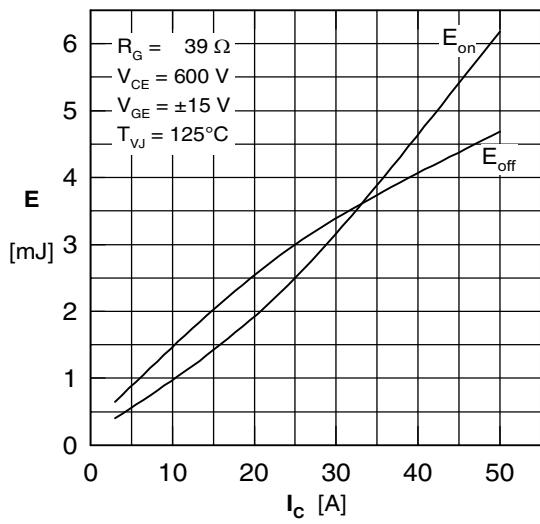


Fig. 5 Typ. switching energy vs. collector current

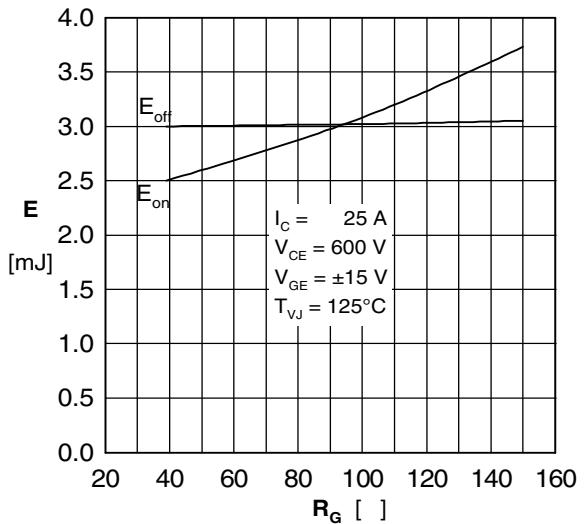


Fig. 6 Typ. switching energy vs. gate resistance

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Inverter D1 - D6

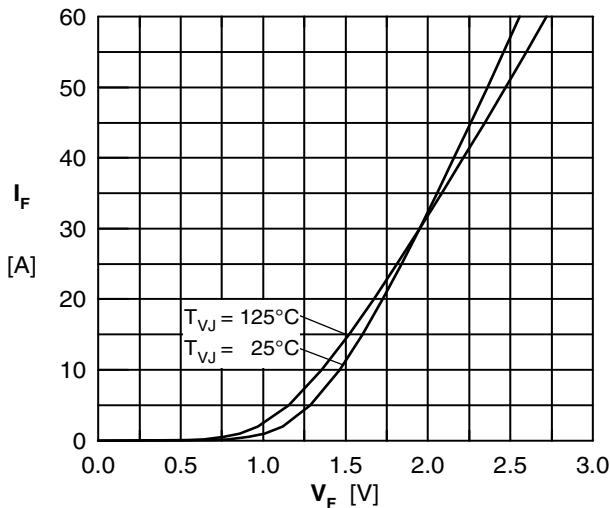
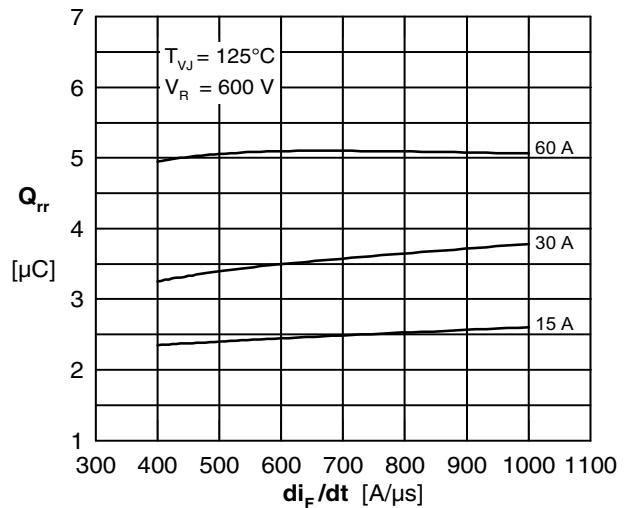
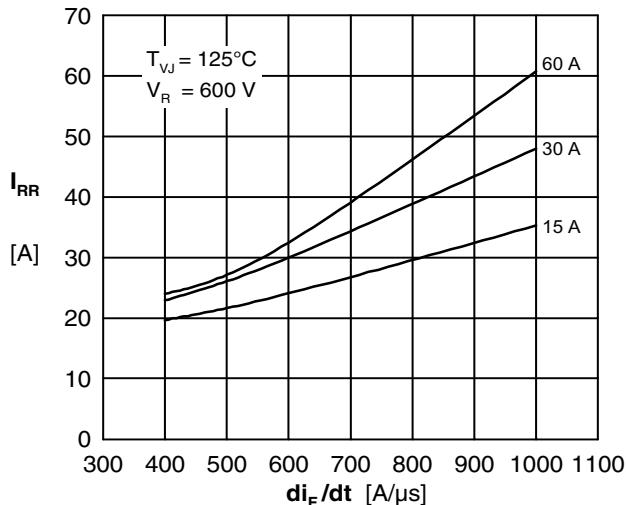
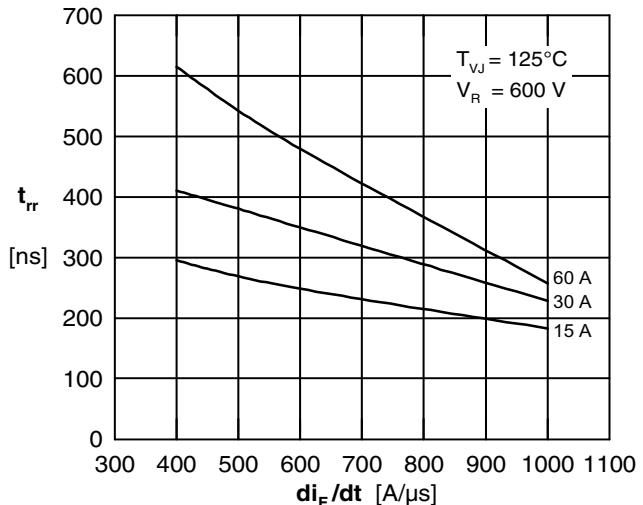
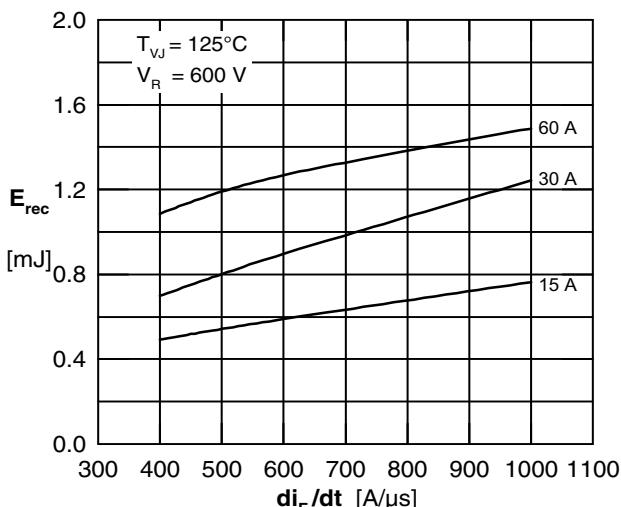
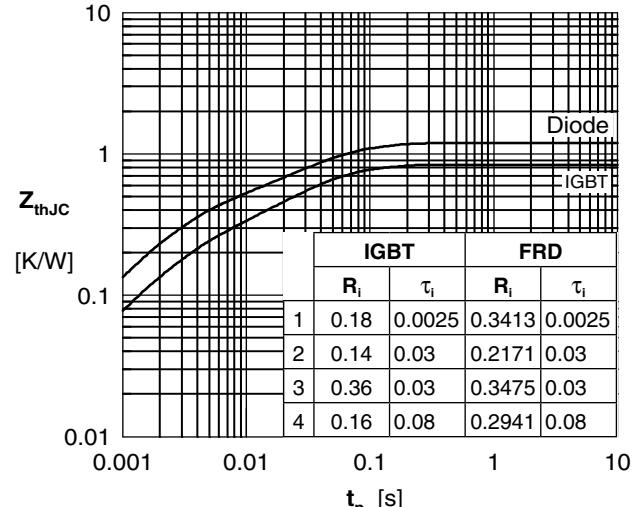
Fig. 7 Typ. Forward current versus V_F Fig. 8 Typ. reverse recov.charge Q_{rr} vs. di/dt Fig. 9 Typ. peak reverse current I_{rrm} vs. di/dt Fig. 10 Typ. recovery time t_{rr} versus di/dt Fig. 11 Typ. recovery energy E_{rec} versus di/dt 

Fig. 12 Typ. transient thermal impedance

IXYS reserves the right to change limits, test conditions and dimensions.

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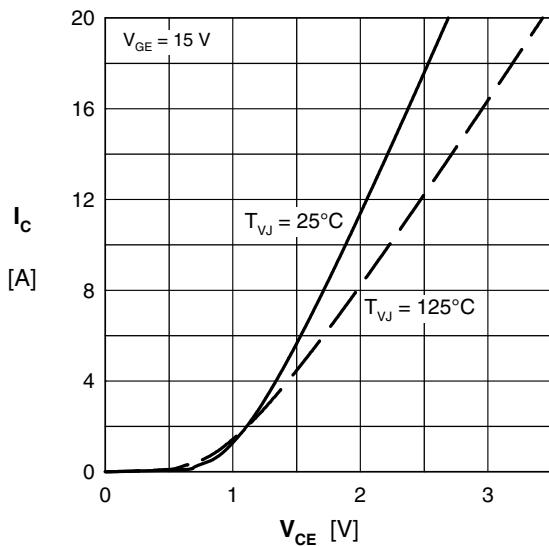
Brake T7 & D7


Fig. 13 Typ. output characteristics

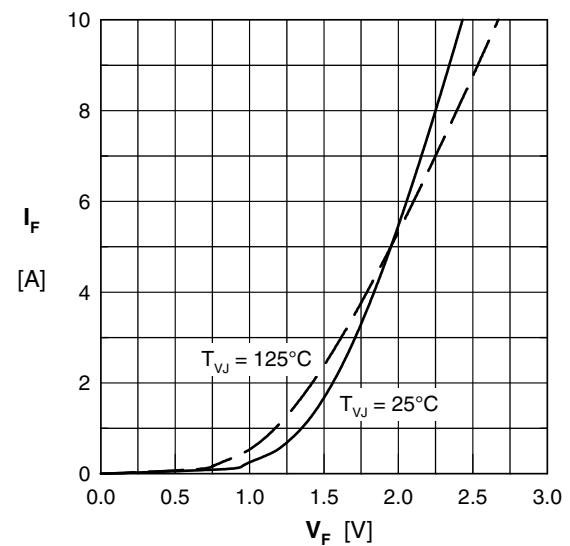


Fig. 14 Typ. forward characteristics

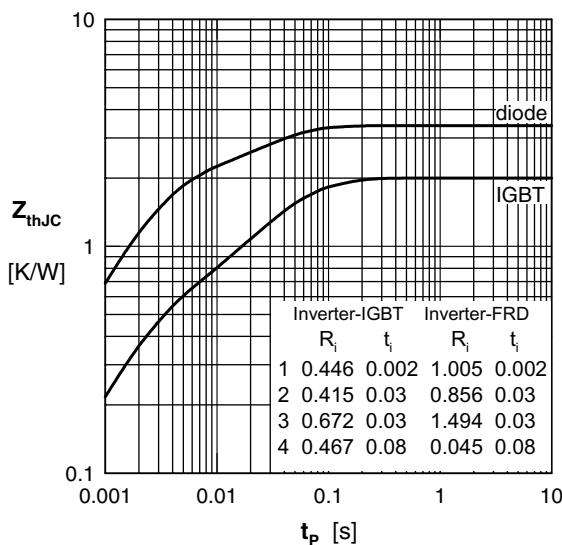


Fig. 15 Typ. transient thermal impedance

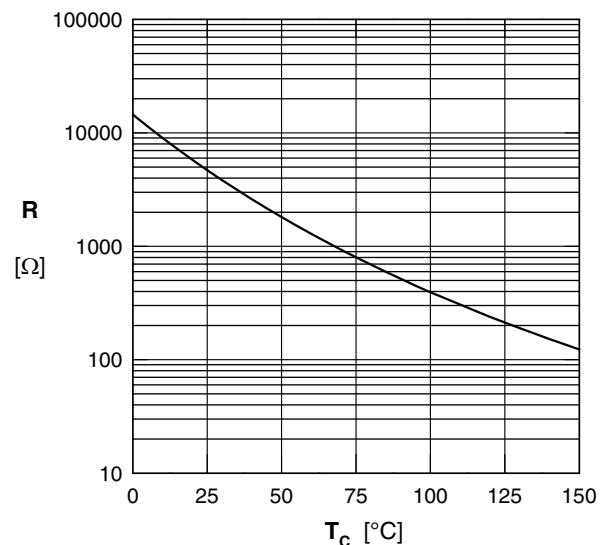


Fig. 16 Typ. NTC resistance vs. temperature